ASSOCIATION CONNECTING ELECTRONICS INDUSTRIES® INTERNATION CONNECTING	burn. Illinois. Al	ll rights reserved un tions.	nder both	This docume evel parts, t	ent is a declaratio he declaration en	n of the substanc compasses all lo	es within the manufactur wer level materials for wl	er listed ite hich the m	em. Note: if anufacturer	the item is an as has engineering	sembly with lower responsibility.	
IPC Web Site for Information on http://www.ipc.org/IPC-175x	Web Site for Information on IPC-1752 Standard Form Type Distribute			k	Declaration Class * Class 6 - RoHS Yes/No, Homogeneous Materials and Mfg Information					on		
Supplier Information												
Company name*	npany name* Company unique ID			Unique ID Authority				Response Date*				
emi									2025-06-06			
Contact Name	Title - Contact			]	Phone - Contact*			Email - Contact*				
Product-Env-Stewards	Product Enviro Compliance				NA				Product-Env-Stewards@onsemi.com			
thorized Representative* Title - Representative				]	Phone - Representative*				Email - Representative*			
Product-Env-Stewards Product Enviro Compliance				NA			Product-Env-Stewards@onsemi.com					
Requester Item Number Mfr Iter	n Number	Mfr Item Name			Effective Date	Version	Manufacturing Site		Veight*	UOM	Unit Type	
SNRVI	JD620CTT4G ULTRAFAST 200V		V 6A		2025-06-06		VN5	3	53.13	mg	Each	
Manufacturing Proccess Information												
Terminal Plating / Grid Array Material	Terminal Base Alloy		-STD-020 MSL	Rating	Peak Proces	ess Body Temperature Max Time at Peak		Temperature Number of Reflow Cycles		eles		
Matte Tin (Sn) - annealed CU Alloy 1					260	С	30	second	ls 3			
Comments												
evel 1 - maximum time at peak temperature during s	dering is 10-30	) seconds										
For more information regarding material composition	please refer to	page 3										

RoHS Material Composition Declaration				Declaration Type *	Detailed				
Directive 2015/863/EU amending RoHS Directive 2011/65/EU		mium (Cr6+), Polybrominated Biphenyls (Pl		dmium and quantity limit of 0.1% by mass (10 minated Diphenyl Ethers (PBDE), and Bis(2-et					
cadmium, hexavalentchromium, polybromina contains a RoHS restricted substance inexces encompass all such components. Supplier cer as of the date that Supplier completes this for Company acknowledges that Supplier may h independently verified information provided certification in this paragraph. If the Company	ated biphenyls and/or polybrominated dip s of an applicable quantity limit, please in iffies that it gathered the information it pr m.Supplier acknowledges that Company ave relied on informationprovided by oth by others, Supplier agrees that, at a minir and the Supplier enter into a written agr esource of the Supplier's liability and the	henyl ethers (each a "RoHS restricted substa ndicate below which, if any, RoHS exemption ovides in this form using appropriate methoo will rely on this certification in determining ers in completing this form, and that Supplie num, itssuppliers have provided certification eement with respect to the identified part, the Company's remedies for issues that arise reg	nce") in exco n you believe ls to ensure i the compliar r may not ha s regarding t terms and co	e may apply. If the part is an assembly with low s accuracy and that such information is true an ce of its products with European Union member de independently verified such information. Ho neir contributions to the part, and those certifica	ove. If a homogeneous material within the part er level components, the declaration shall d correct to the best of its knowledge and belief, er state laws that implement the RoHS Directive. wever, in situations where Supplier has not ations are at least as comprehensive as the anty rights and/or remedies provided as part of				
RoHS Declaration * 4 - Item(	s) does not contain RoHS restricted subst	ances per the definition above except for sele	ected exempt	ions Supplier Acceptance	* Accepted				
Exemption: 7a: Lead in high melting temperature type solders (i.e. lead based solder alloys containing 85% by weight or more lead).									
Exemption List Version	EL-2011/534/EU								
Declaration Signature									
Instructions: Complete all of the required Requester) and click on Submit Form to h			e drop-dowi	a. This will display the signature area. Digita	lly sign the declaration (if required by the				
Supplier Digital Signature	astislav Drska	Le							

## Homogeneous Material Composition Declaration for Electronic Products

SubItem Instructions: The presence of any JIG Level A or B substances must be declared. [1] indicate the subpart in which the substance is located, [2] provide a description of the homogeneous material [3], enter the weight of the homogeneous material.

Homogeneous Material	Weight	Unit of Measure	Level	Substance	CAS	Exempt	Weight	Unit of Measure
Die	1.2	mg	Supplier	Silicon (Si)	7440-21-3		1.2	mg
Die Attach 1	1.4	mg	А	Lead (Pb)	7439-92-1	7a	1.33	mg
			Supplier	Tin (Sn)	7440-31-5		0.07	mg
Lead Frame 2	214.64	mg	В	Nickel (Ni)	7440-02-0		0.4293	mg
			Supplier	Copper (Cu)	7440-50-8		214.2107	mg
Mold Compound-Black	128.65	mg		Epoxy resin	proprietary data		3.8595	mg
			Supplier	Phenolic Resin	Proprietary Data		1.9297	mg
			Supplier	Silica Amorphous (SiO2)	7631-86-9		19.2975	mg
			Supplier	Carbon Black (C)	1333-86-4		0.6432	mg
			Supplier	Fused Silica (SiO2)	60676-86-0		102.92	mg
Plating	3.73	mg	Supplier	Tin (Sn)	7440-31-5		3.73	mg
Wire Bond - Al	3.51	mg	Supplier	Aluminum (Al)	7429-90-5		3.51	mg

Substance Instructions: [A] select the Level (JIG A, JIG B, Requester or Supplier) [B] select the substance category (JIG or Requester) or enter a value (Supplier). [C] select the substance (JIG) or enter the substance and CAS (Other). [D] select a RoHS exemption, if applicable [E] enter the weight of the substance or the PPM concentration [F] Optionally enter the positive (+) and negative (-) tolerance in percent (Note: percent tolerance values are expected to cover a 3 signar range of distribution unless otherwise noted)